

TEST RESULTS CONCERNING PLASTI DIP CHEMICAL RESISTANCE



CHEMICAL USED	STRENGTH	TEMPERATURE	RESISTANCE
Ferric Chloride	100 %	150 degrees F.	Slight staining and softness of film
H2SO4	5 %	100 degrees F.	Pass
Potassium Hydroxide	3 %	150 degrees F.	Pass
Potassium Permanganate	3 %	150 degrees F.	Film stable – noticed staining
Sodium Hydroxide	10%	210 degrees F.	Noticed softness of film
Hydrochloric Acid	100 %	Room Temp.	Pass
Oxalic Acid	50 %	Room Temp.	Film stable in chemical/water solution
Fluoroboric Acid	25 %	Room Temp.	Pass
Tin/Lead – salt plating solution	100 %	Room Temp.	Pass
Copper – salt plating solution	100 %	Room Temp.	Pass
Gold Cyanide – plating solution	100 %	140 degrees F.	Pass
Sodium Carbonate	100 %	210 degrees F.	Pass
Sodium Hydroxide	10 %	120 degrees F.	Noticed softness on film
Ammonia Hydroxide	100 %	100 degrees F.	Pass
Methyl Ethyl Ketone	100 %	Room Temp.	Fail
Ethyl Alcohol	100 %	Room Temp.	Pass

Ref. www.Performix.com